



LT ELEKTRONIK has been established in 1997 as a service provider for development and production of electronic devices in a wide range of applications. We offer to our clients a large service package in the complete field of electronic manufacturing services including innovative hard- and software solutions.

Range of services:

1. Development and design of electronic devices acc. to customer's specifications
 - circuit design
 - layout
 - EMC conformity
 - prototyping
 - test
2. Production of small-, medium- or large sized series
3. Purchasing of materials
4. Design and construction of test equipment for functional test
5. After sales service

The best solution:

We are able to manufacture the new products in small-, medium- or large sized series. Our engineers can support the new project in all phases during project life cycle. They support the clients at implementation of measures to minimize the costs of serial production. We work in this field of business as a service provider for our clients.

Purchasing:

Purchasing of materials at international sources

We purchase materials at international sources. **LT ELEKTRONIK** has build up long lasting relationships to international sources for buying components guaranteeing delivery in time, highest quality and competitive prices.

All under control:

Test of devices

The assembled PCBs are tested on correct assembly by AOI systems. Computer aided test automats guarantee a comprehensive electric test of the devices free of subjective influences. The inspection of solder spots at components like FBGAS or BGAS is done by x-ray AOI.

Production technique:

Space saving mikrosystem solutions

The assembly of the devices is possible in SMD-, THT- and COB technology. We can process SMD components with packages from 0201 to CSP, OFP, BGA, μ BGA and Flip Chip. Very latest solder technologies like selective soldering, vapour phase soldering, wave soldering and reflow soldering enable a careful processing of the components and reliable contact between the components and the PCB.

Chip on board technology

We create space saving mikrosystem solutions for our clients by chip on board technology. The production is carried out by highly precise equipment in following steps:

DIE BONDING:

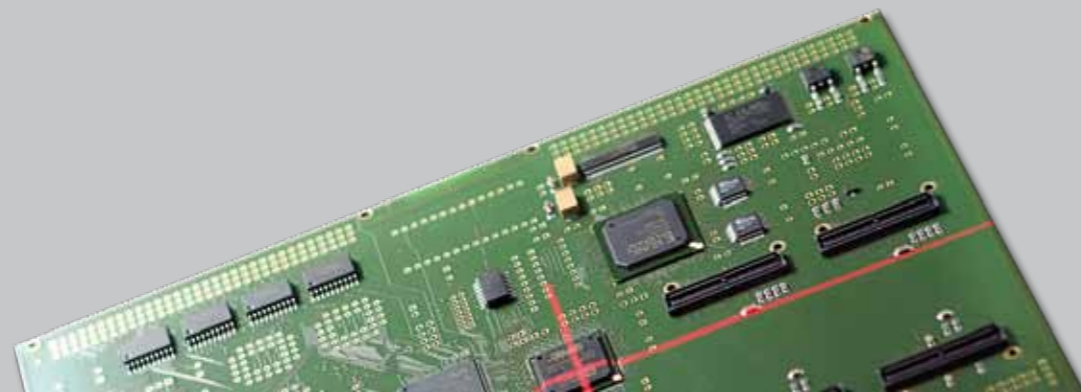
- wafer and discrete component level process
- clue stamping or dispensing
- source package blue tape, gel pack , wafer pack
- wafer mapping functionality

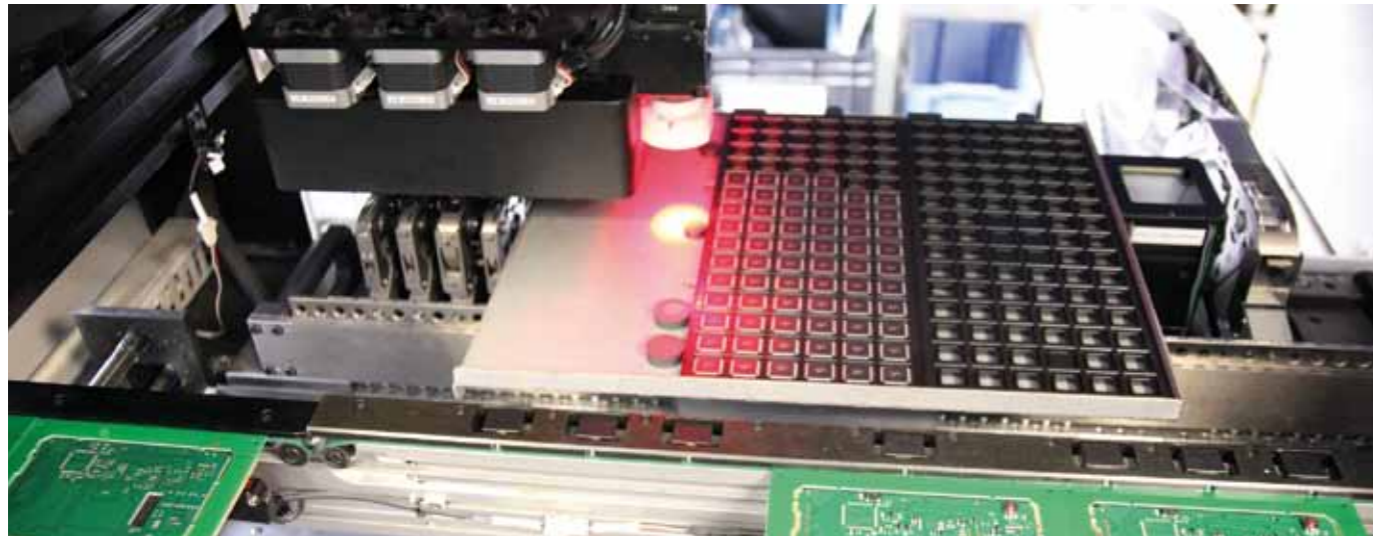
WIRE BONDING:

- discrete component level process
- ball/ wedge, wedge/wedge applications
- gold and aluminium wire bonding
- wire diameter from 17 μ m up to 75 μ m
- deep access capability
- wafer mapping functionality

GLUING:

- gluing of patterns and globe tops
- easy adaptation for different kinds of patterns
- various kinds of glue
- thermo and UV curing



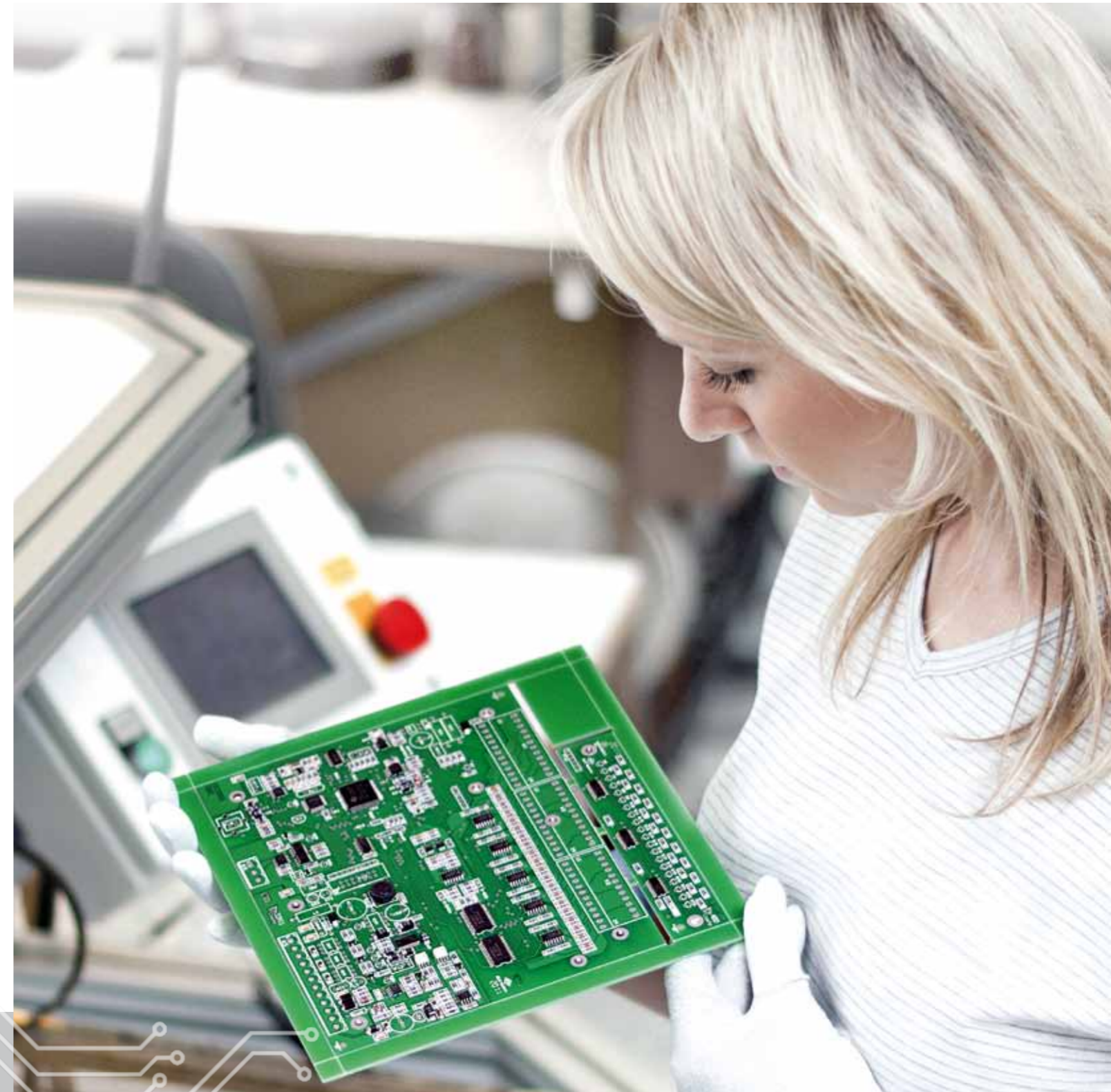


Quality:

Our clients appreciate the high quality and delivery reliability of our products. From the beginning of the development the sustainability of the devices is very important for us. The production site is certified acc. to ISO 9001 : 2009. Regular in - company trainings of the staff ensure permanent quality improvements of the product and a high quality awareness.

Environmental protection

The production is carried out in compliance with the environmental standards and rules. All products, being delivered are RoHS conform.



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innovative - flexible - reliable